

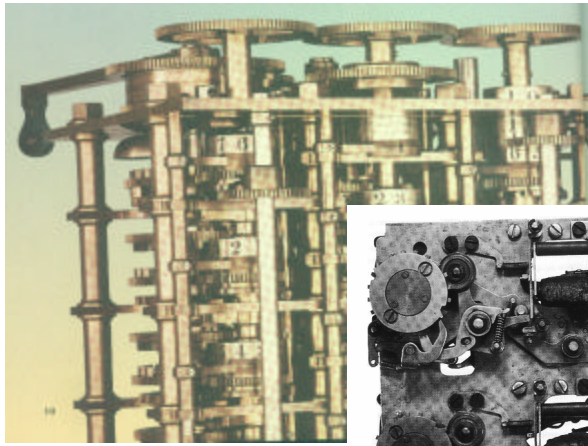


IBM T. J. Watson Research Center

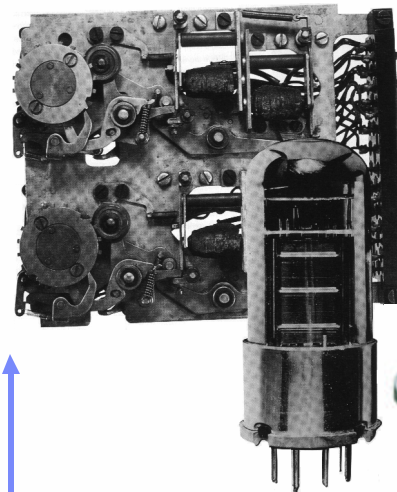
The Future of Electronics: Post-Silicon Logic and Memory

Thomas N. Theis,
Director, Physical Sciences, IBM Research

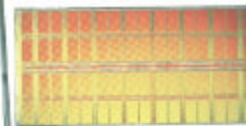
Can we extend the IT revolution?



principle
features
specified to: $\times 1\text{mm}$



$\times 10\ \mu\text{m}$



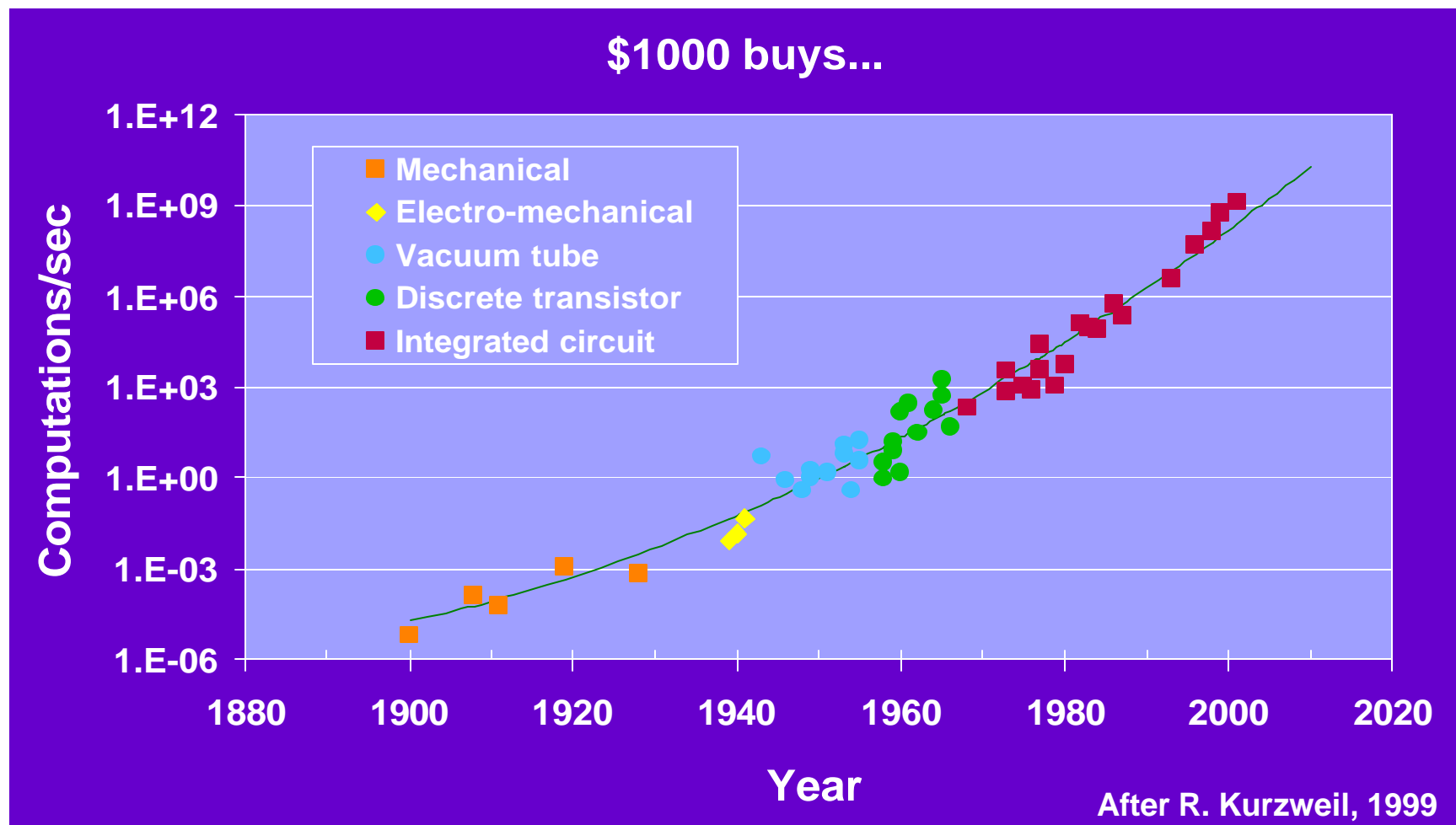
$\times 100\ \text{nm}$

Information technology has progressed through continuous miniaturization and repeated invention of new devices to store, process, and communicate information. The transistor and other devices are now approaching hard physical limits.

What's Next?

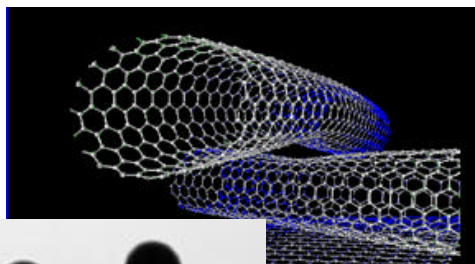
Organic Electronics?
Moletronics?
Spintronics?
Plasmonics?
Quantum Computing?
...?

Result: Ever-Decreasing Costs of Computation, Ever-Expanding Applications of Information Technology

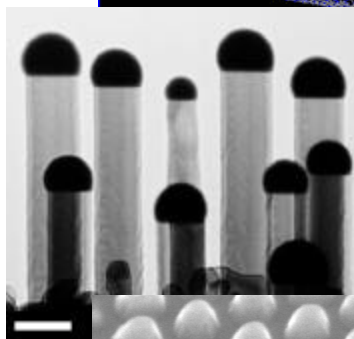


Needed: New Devices Based on New Materials and New Physics.

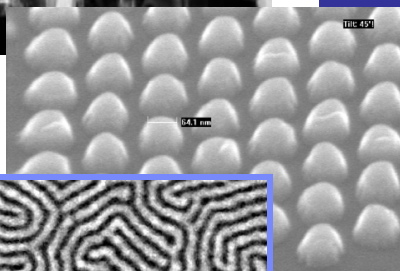
Carbon
nanotubes



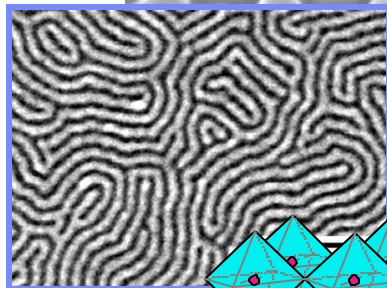
Semiconductor
nanowires



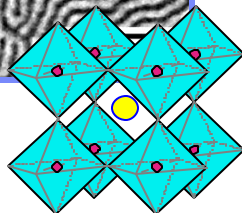
Chalcogenides



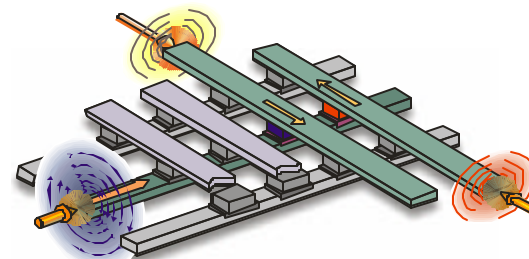
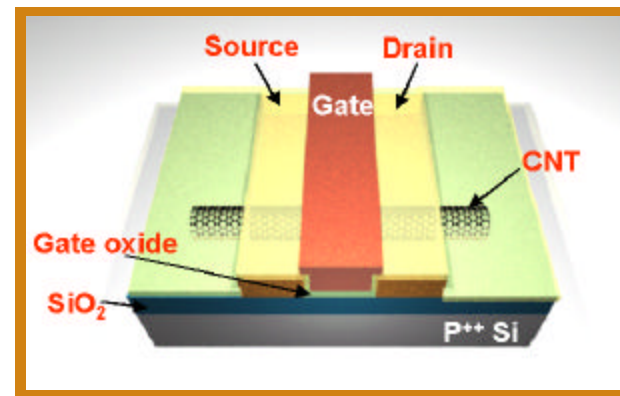
Polymers



Complex Oxides



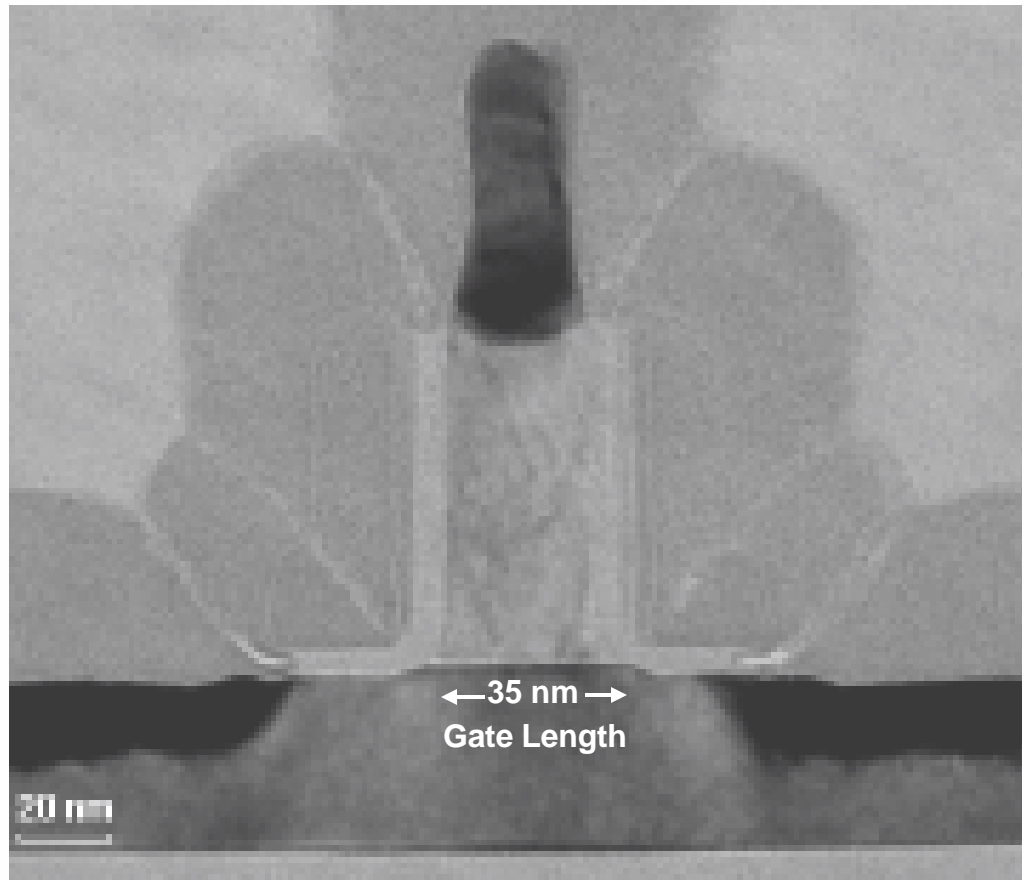
New (smaller,
cheaper, faster)
devices



Topics

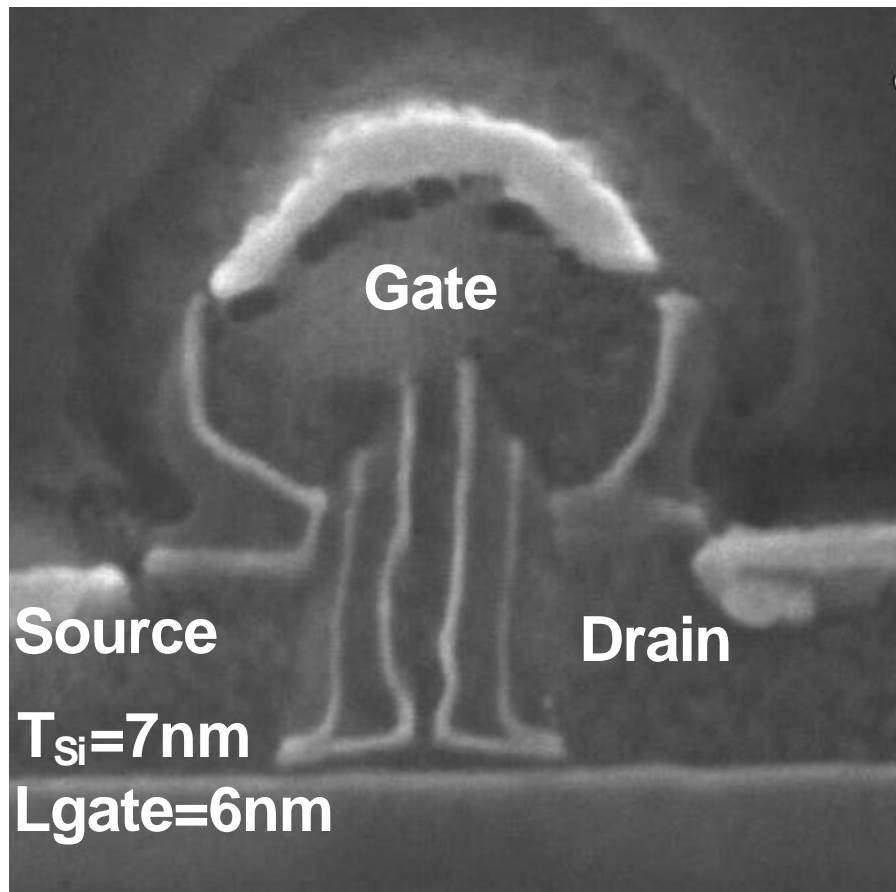
- The extension of silicon CMOS technology
- The search for the “ultimate” FET
- “Beyond the FET”:
the Nanoelectronics Research Initiative
- A Personal Outlook:
prospects for adiabatic switching and reversible logic

The silicon transistor in manufacturing ...



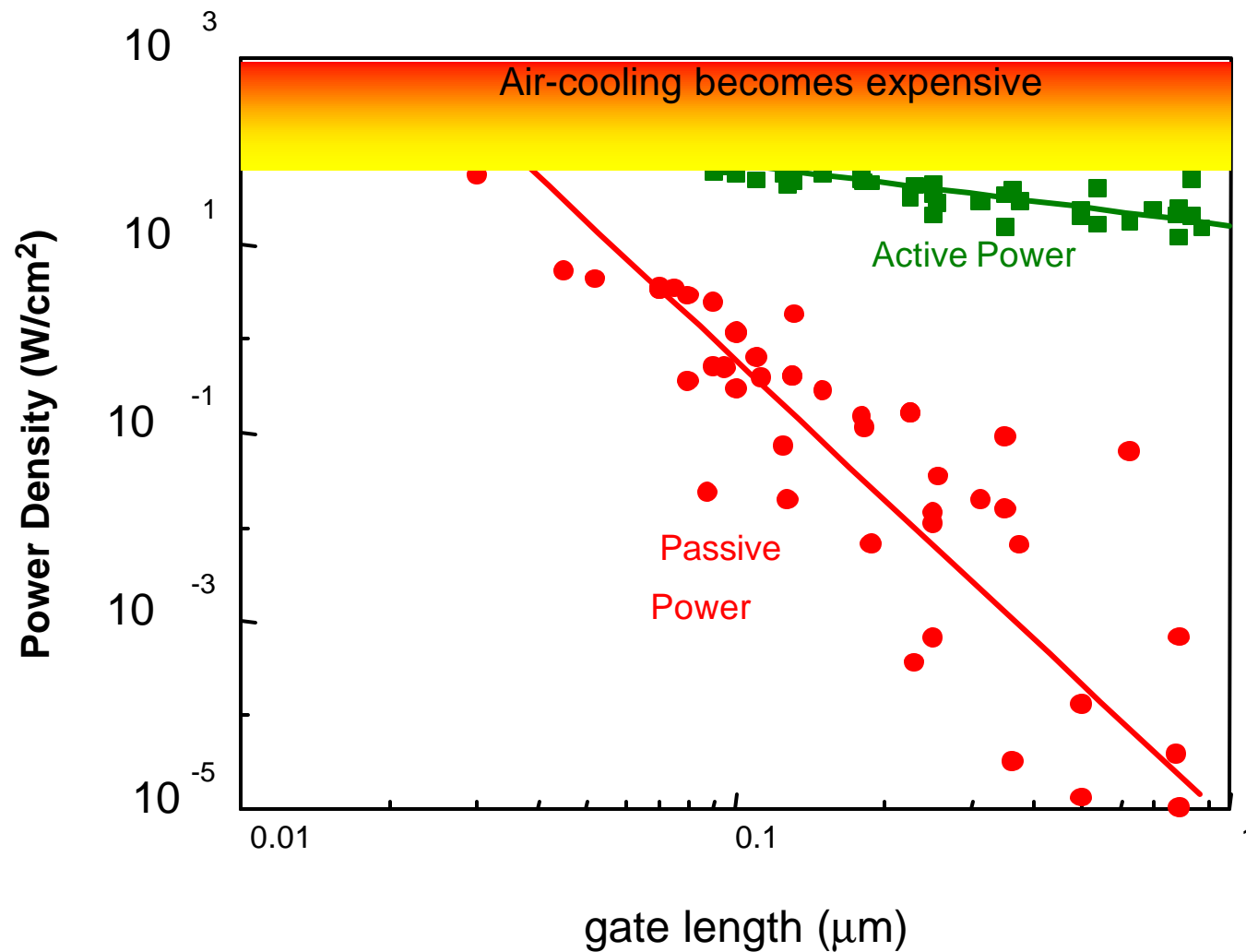
90 nm technology generation

... and in the lab.

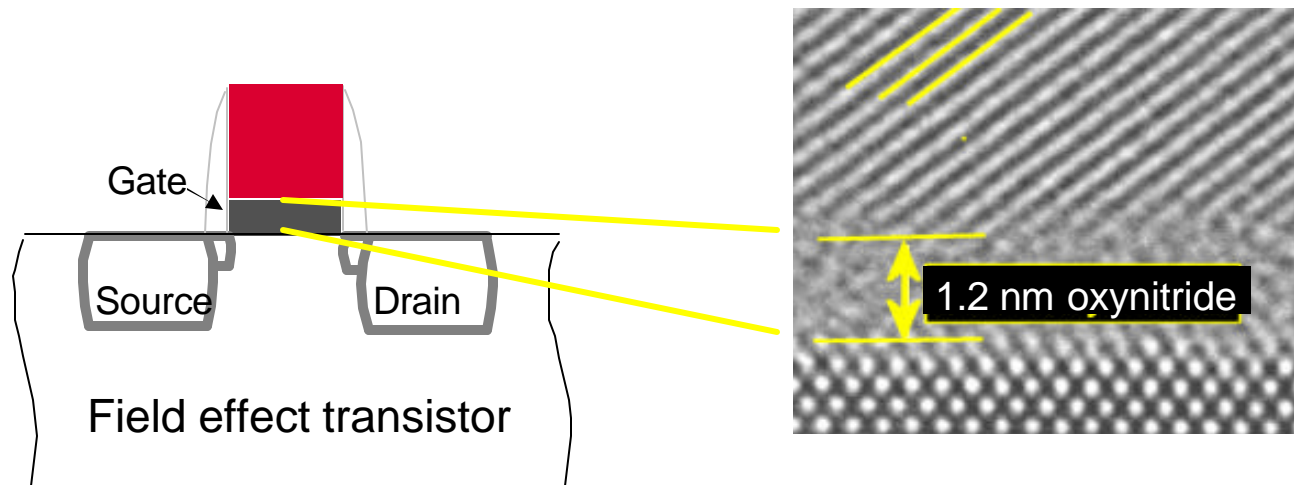


B. Doris et al., *IEDM*, 2002

Still, we are approaching some limits.

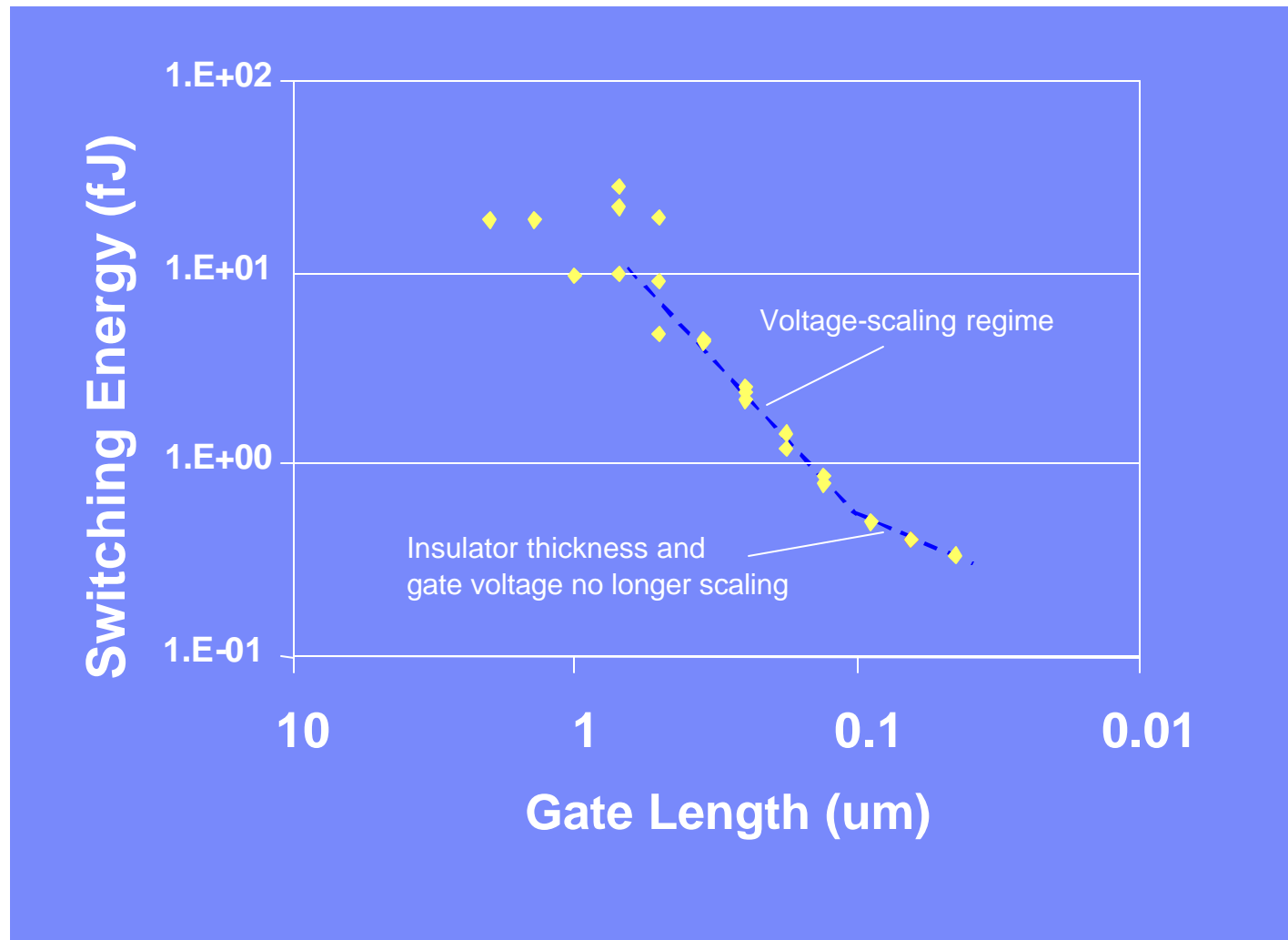


The Problem with Passive Power Dissipation: The Inability to Scale Atoms

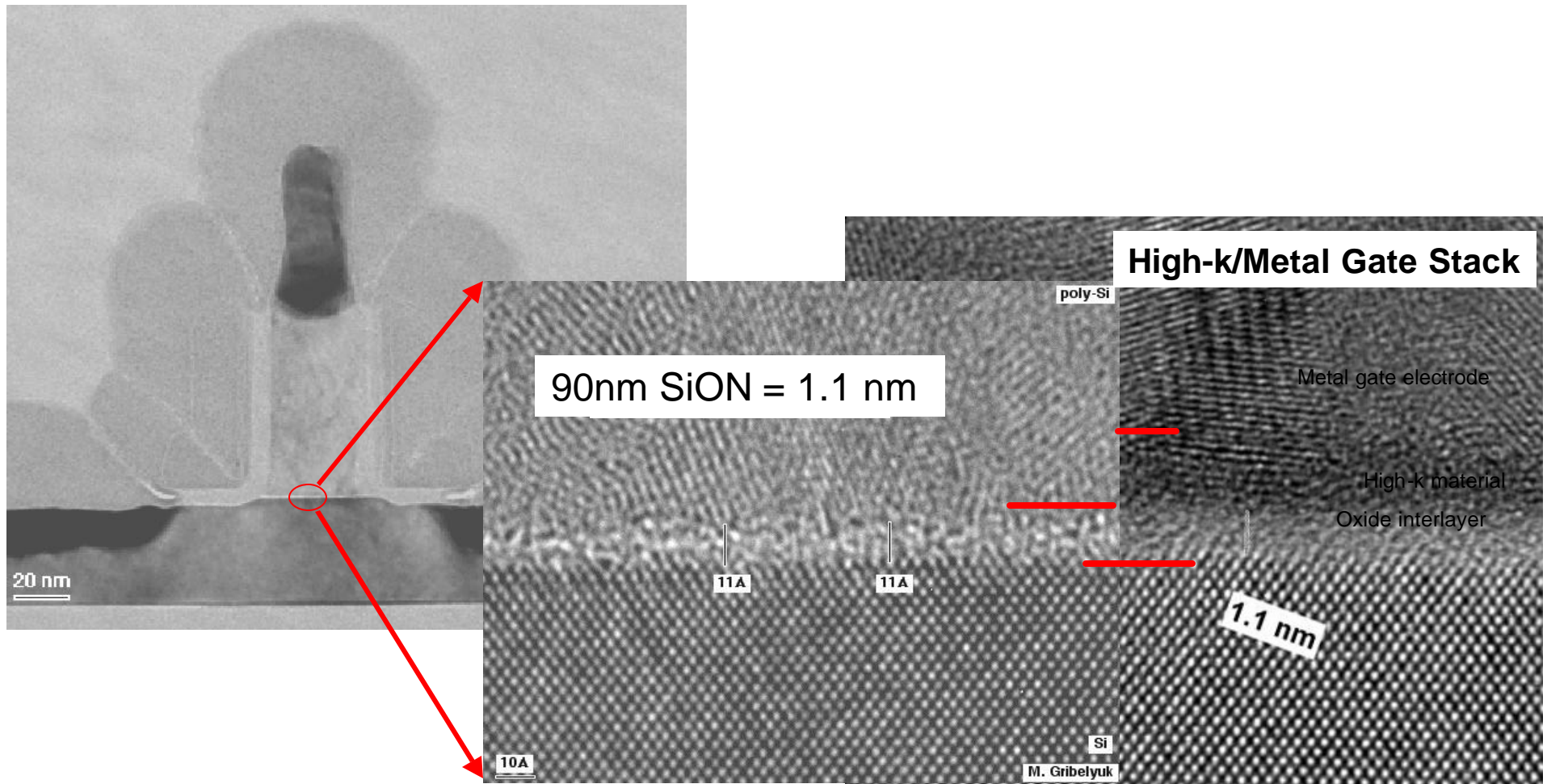


- Direct tunneling through the gate insulator will be the dominant cause of static power dissipation.
- Single atom defects can cause local leakage currents 10 – 100x higher than the average current, impacting reliability and generating unwanted variation between devices.

Switching energy is declining at a slower rate.



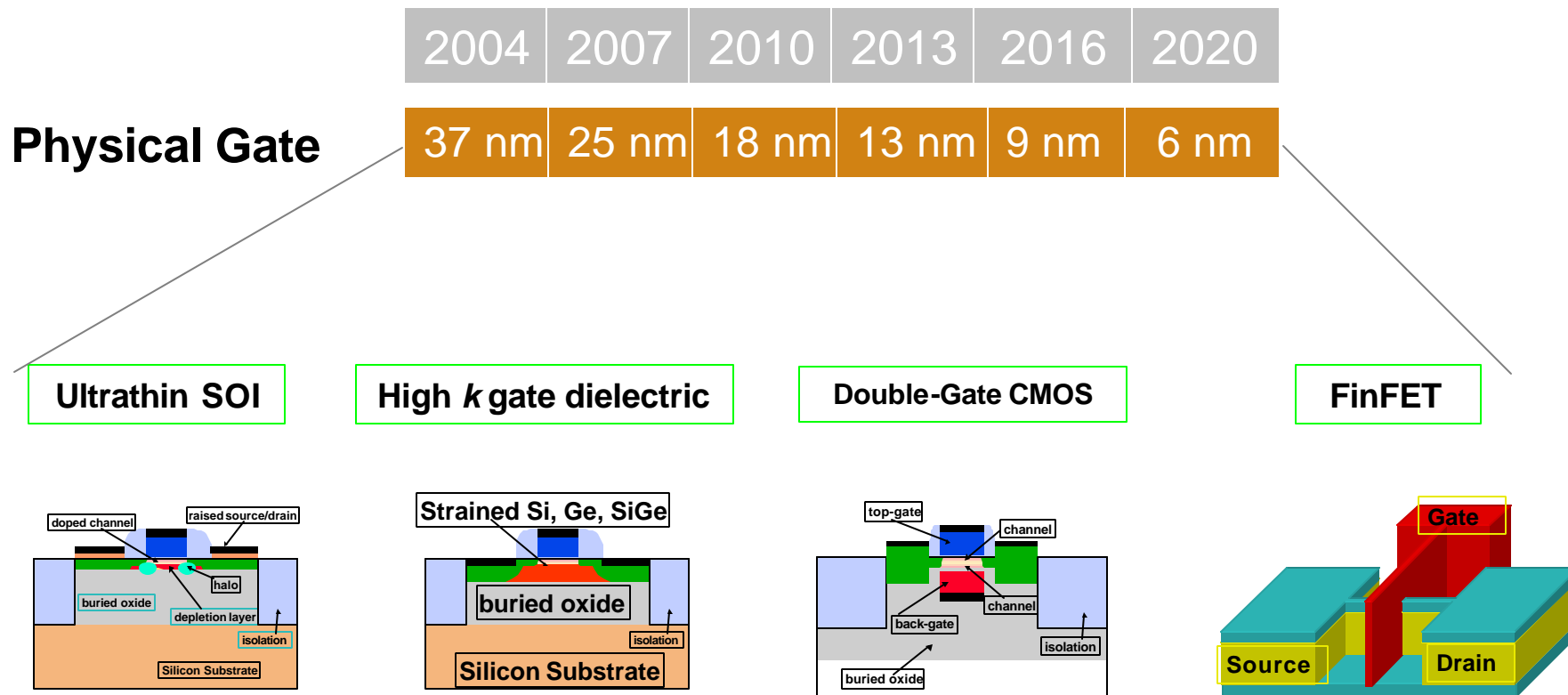
The Work-Around: High-k Insulator / Metal Gate Stack



90nm Gate Dielectric:
 $T_{inv} = 19\text{\AA}$
 $T_{oxGL} = 11\text{\AA}$

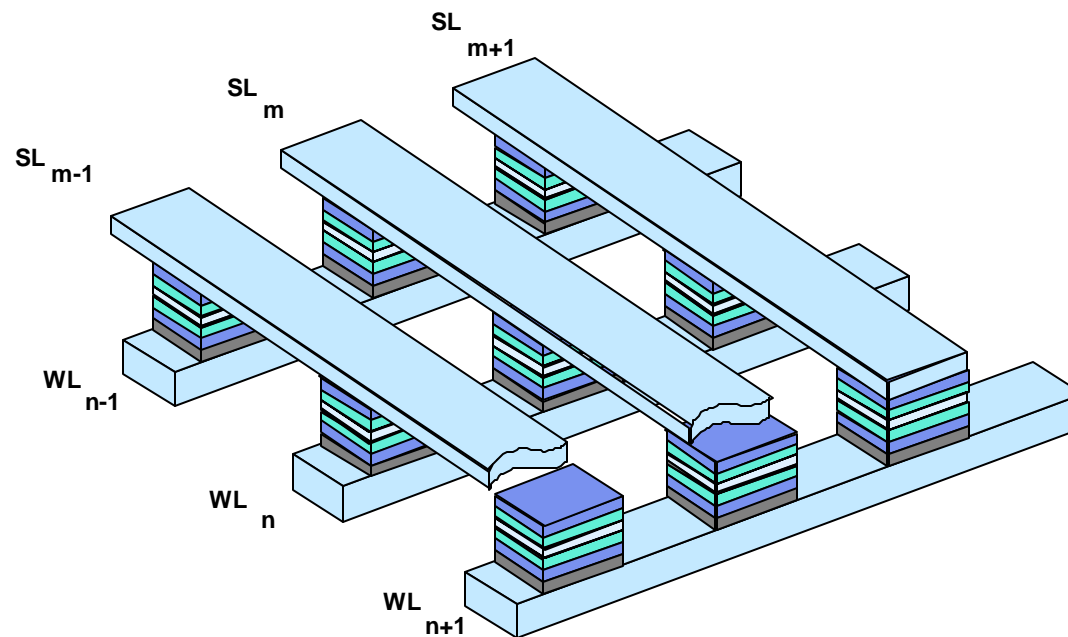
High-k/Metal Gate Stack:
 $T_{inv} = 14.5\text{\AA}$
 $T_{oxGL} = 16\text{\AA}$

Innovation Will Continue: Transistor Roadmap Options



In general, growing power dissipation and increasing process variability will be addressed by introduction of new materials and device structures, and by design innovations in circuits and system architecture.

Memory may be easier to shrink than logic.

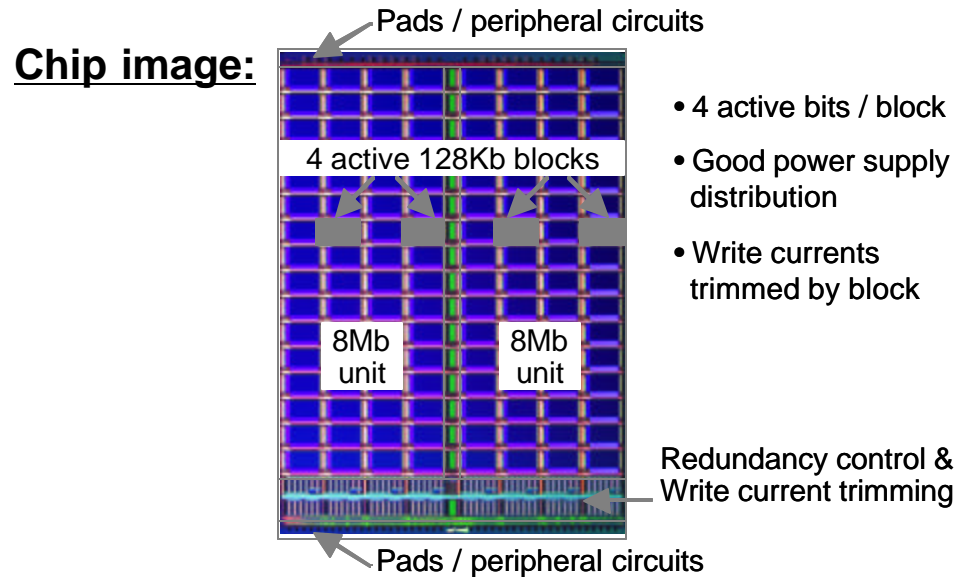


- Everyone is looking for a dense (cheap) cross-point memory.
- It is relatively easy to identify materials that show bistable hysteretic behavior (easily distinguishable, stable on/off states).

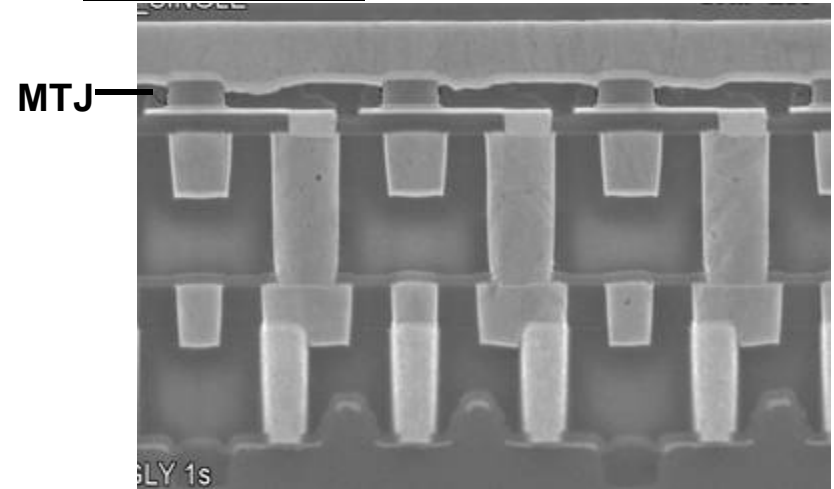
Some Classes of Novel Memory Devices Under Development by Commercial Entities

- Extensions of Silicon Nonvolatile (Flash) Memory
- Magnetic Tunnel Junctions (MRAM)
- Chalcogenide Phase Change Materials (PCM)
- Ferroelectric Polymers
- Hysteretic Conduction in Complex Metal Oxides
- Solid-State Electrochemical Systems
- (Nano) Electro-Mechanical Systems
- and more ...

Example: 16Mbit IBM MRAM Demonstration

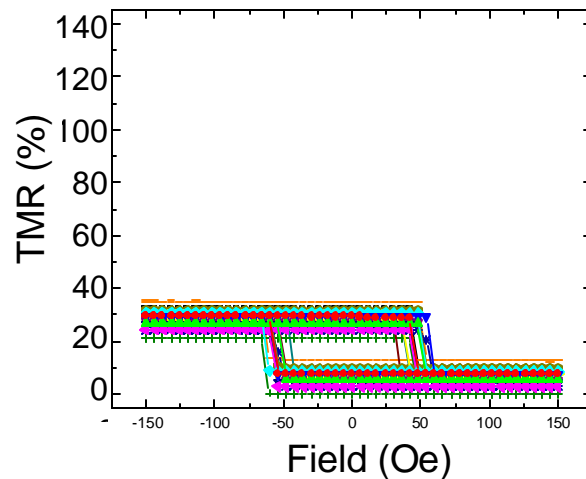


Cross-section:

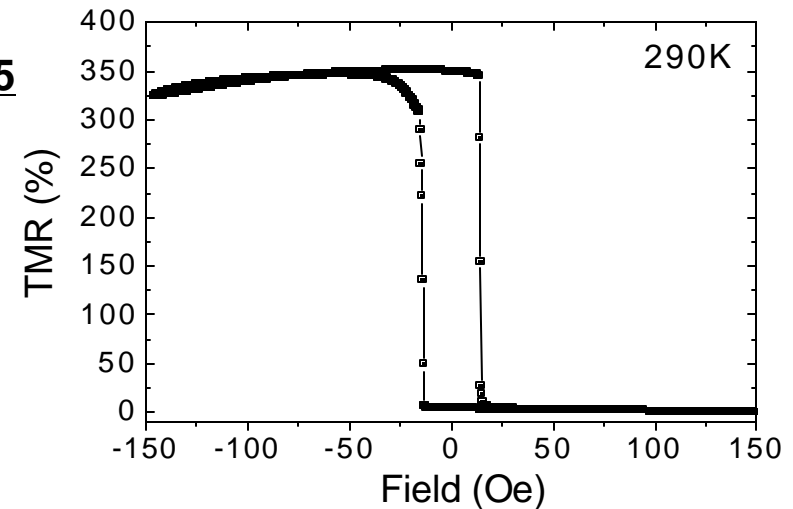


Materials Advances

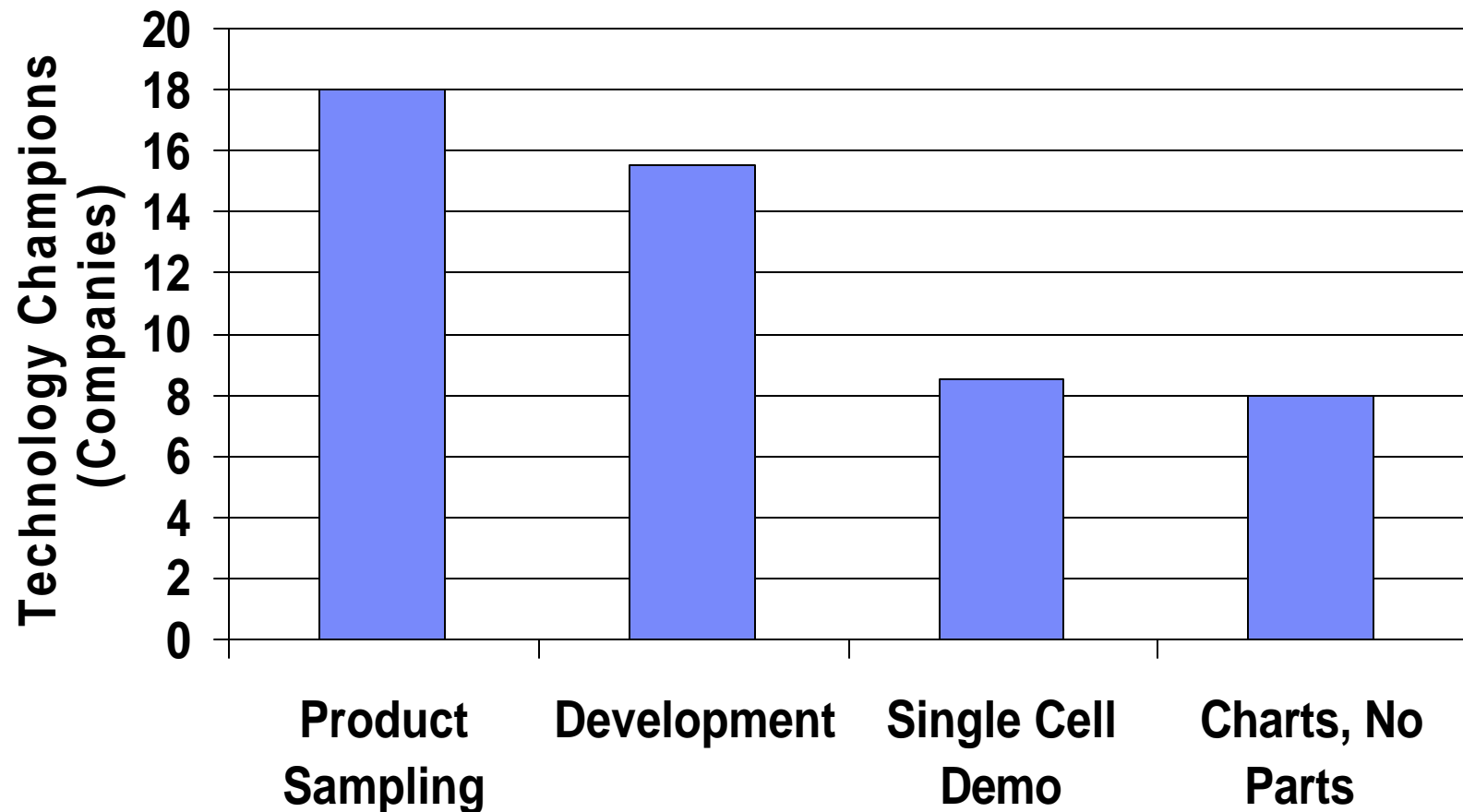
1995



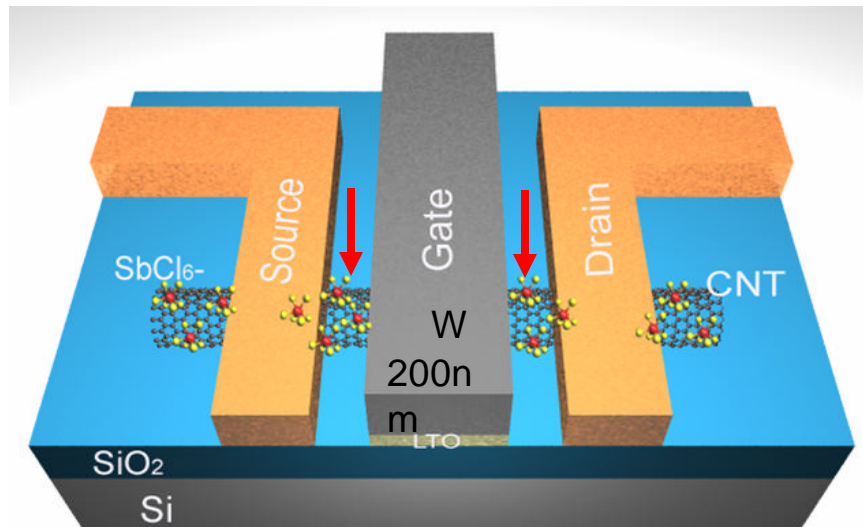
2005



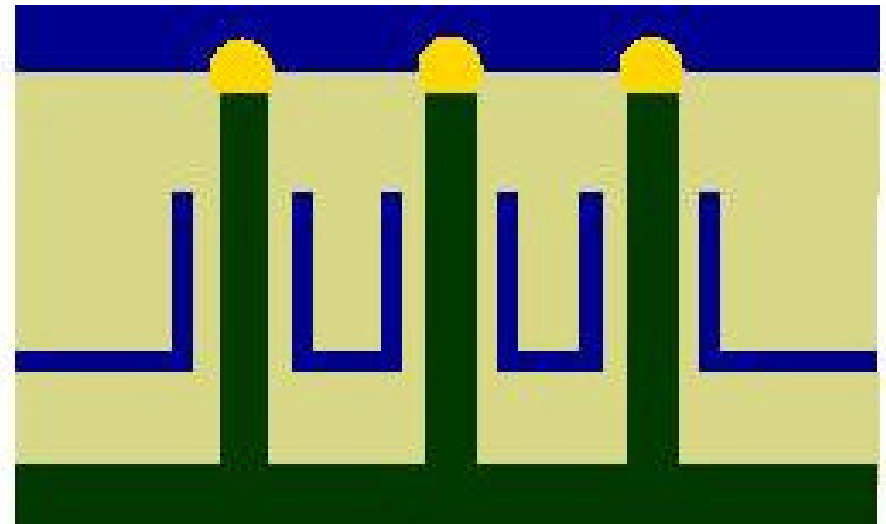
Relative Maturity of Nonvolatile Memory Technologies (2005)



Post-Silicon CMOS: The Quest for the Ultimate FET

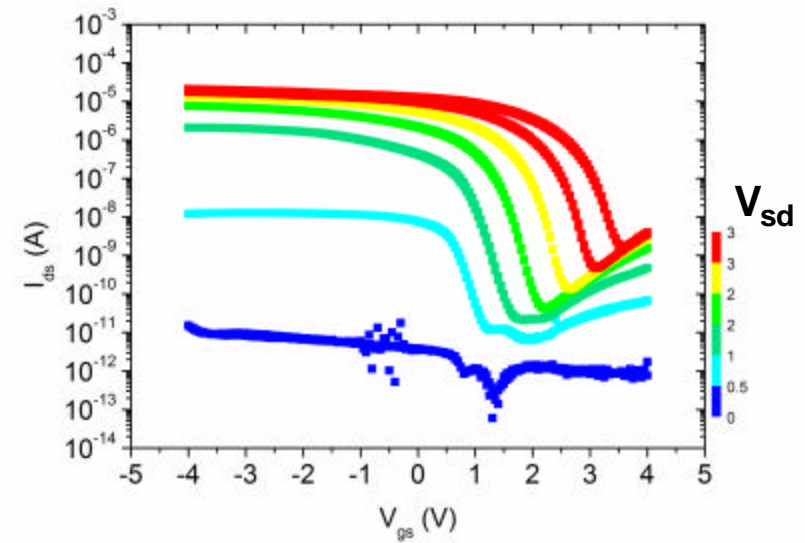
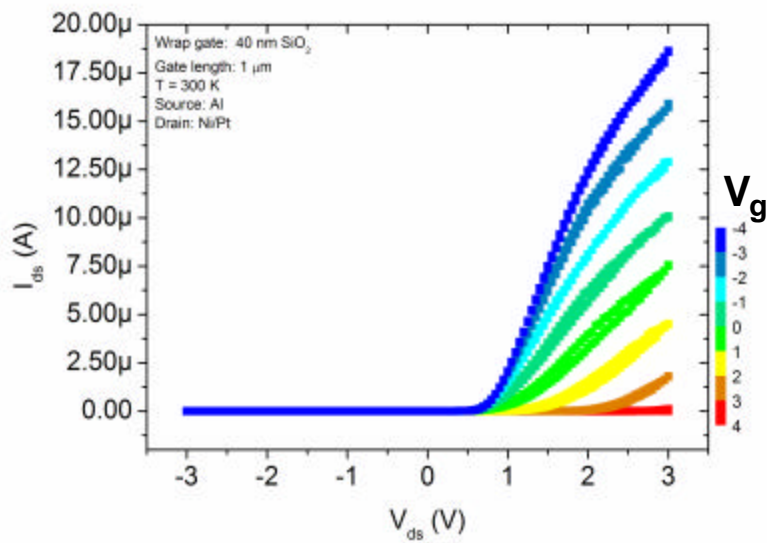
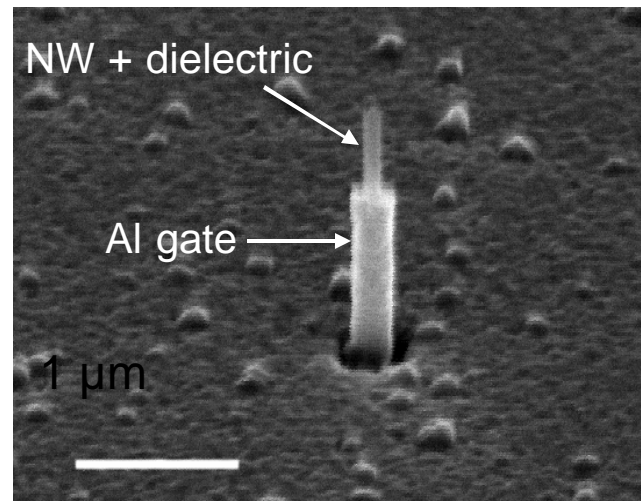


Self-Aligned Carbon Nanotube FET:
Extension Contacts Based on
Charge-Transfer Chemical Doping



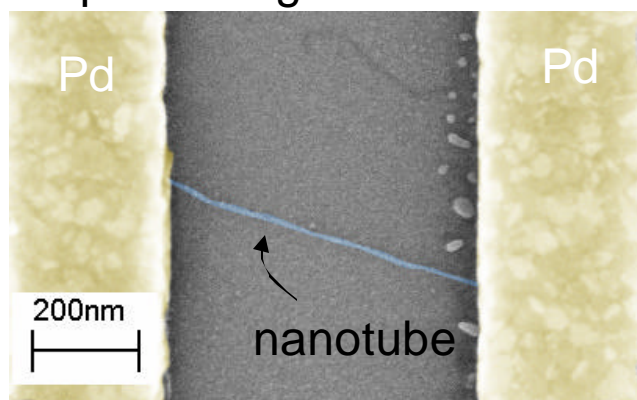
Vertical Transistor
Based on Semiconductor Nanowires

Vertical Silicon Nanowire FET

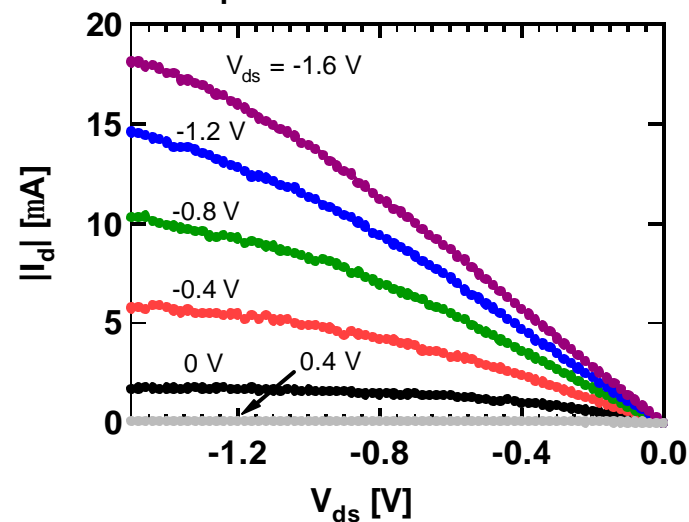


Intrinsic Performance of Carbon Nanotube FETs

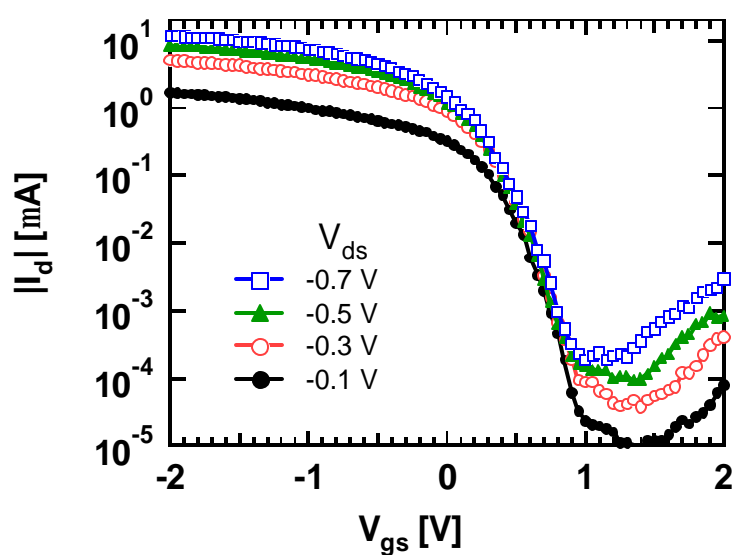
Simple back-gated CNTFET



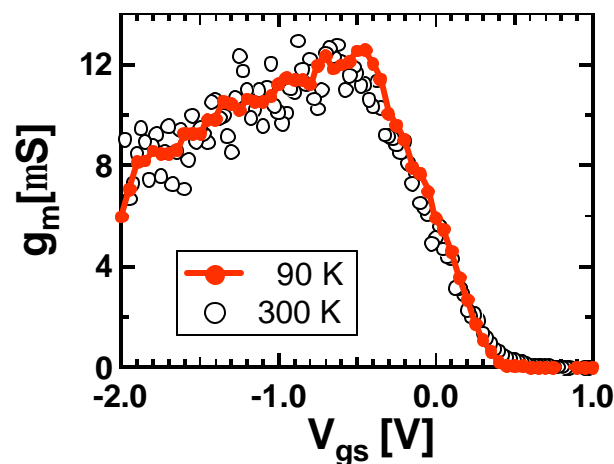
Output Characteristics



Subthreshold Characteristics



Temperature dependence



Yu-Ming Lin *et al.* (IBM), EDL 2005

Intrinsic Switching Speed of CNFETs

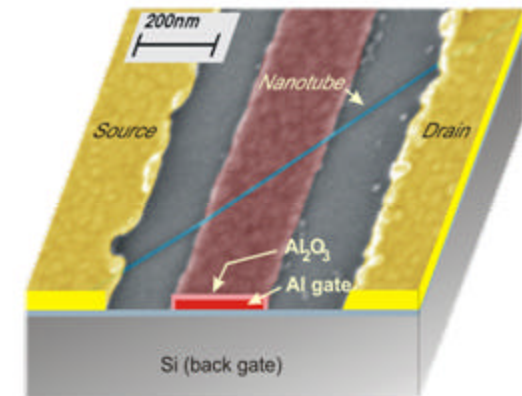
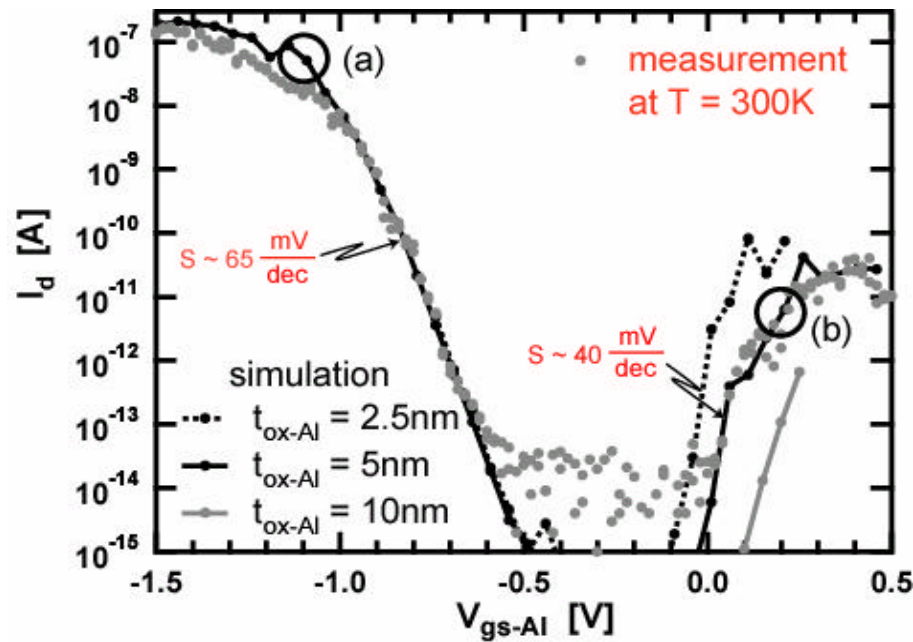
Cut-off Frequency $f_T = \frac{g_m}{2pC_g}$ C_g : gate capacitance

	Lin et al. (IBM)	Javey et al. (Stanford)	Seidel et al. (Infineon)
Diameter	~ 1.8 nm	~ 1.7 nm	~ 1.1 nm
Gate Dielectric	10-nm SiO ₂	8-nm HfO ₂	12-nm SiO ₂
Maximum g_m	12.5 μ S	27 μ S	3.5 μ S
C_g/L	38 pF/m	120 pF/m	32 pF/m
f_T @ $L_g = 65$ nm	800 GHz	550 GHz	260 GHz

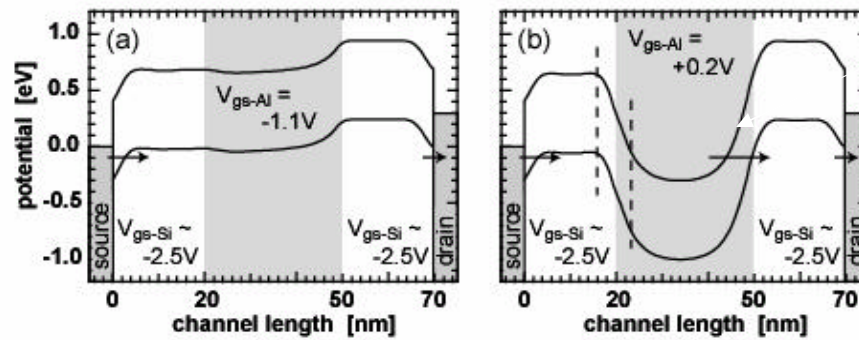
Yu-Ming Lin *et al.* (IBM), EDL 2005

Carbon Nanotube FET:

Potential for greatly improved turn-on characteristics (low-voltage operation)



Dual-Gate
CNTFET



J. Appenzeller, Y.-M. Lin,
J. Knoch, and Ph. Avouris,
Phys. Rev. Lett. **93**, 196805 (2004)

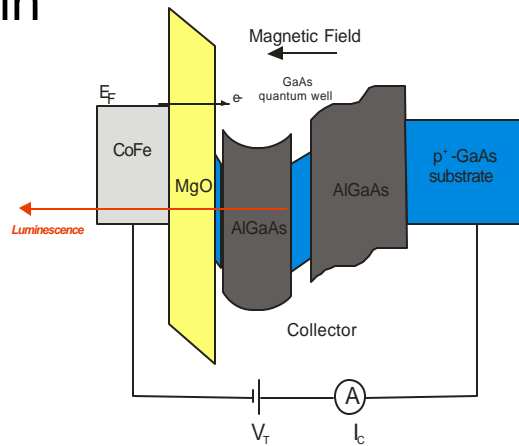
Will there be a successor to the FET?

- Many have written about this subject.
- An article by George Bourianoff (“The Future of Nanocomputing”, IEEE Computer 36, pp. 44–53) sparked discussions within the Semiconductor Research Corporation regarding the objectives of a new research program – the Nanoelectronics Research Initiative (NRI) – which would stimulate the exploration of devices “beyond the FET”.

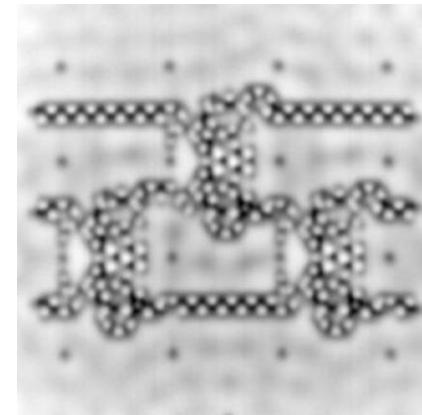
→ computational state vectors other than electronic charge

Beyond Charged-Based Logic?

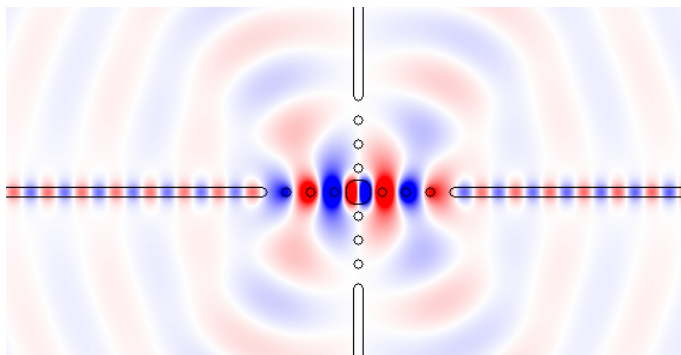
■ Spin



■ Nanomechanics



■ Photons and Plasmons



■ Biochemistry



Nanoelectronics Research Initiative (NRI)

- AMD, Freescale, Micron, TI, IBM, Intel
→ Joint Industry funding of University Research
- Promoting both
 - Invention / Discovery (distributed research, “let many flowers bloom”)
 - Proof of Concept (focused university consortia with outstanding facilities)
- “Extend the historical cost/function reduction, along with increased performance and density ... orders of magnitude beyond the limits of CMOS”
 - Computational State Vectors other than Electronic Charge
 - Non-equilibrium Systems
 - Novel Energy Transfer Mechanisms
 - Nanoscale Thermal Management
 - Directed Self-assembly of such structures

Nanoelectronics Research Initiative (NRI):

Announced Dec. 8, 2005, at *Silicon Nanoelectronics and Beyond*, by NSF and SRC

- Institute for Nanoelectronics Discovery and Exploration (INDEX)
 - Lead Institution: College of Nanoscale Science and Engineering at the University of Albany (SUNY)
 - MIT, Georgia Institute of Technology, Harvard, RPI, Yale, Purdue
 - **Spintronic** and molecular **configurational** switches
- Western Institute of Nanoelectronics (WIN)
 - Lead Institution: UCLA Henry Samueli School of Engineering and Applied Science
 - UCLA, UC Berkeley, UC Santa Barbara, Stanford
 - **Spintronic** and **plasmonic** devices
- Southwestern Academy of Nanoelectronics (SWAN)
 - Lead Institution: UT Austin Microelectronics Research Center
 - Texas A&M, UT Dallas, ASU, Notre Dame, U. of Maryland, Rice U.
- Supplemental NSF/NRI grants to existing NSF centers

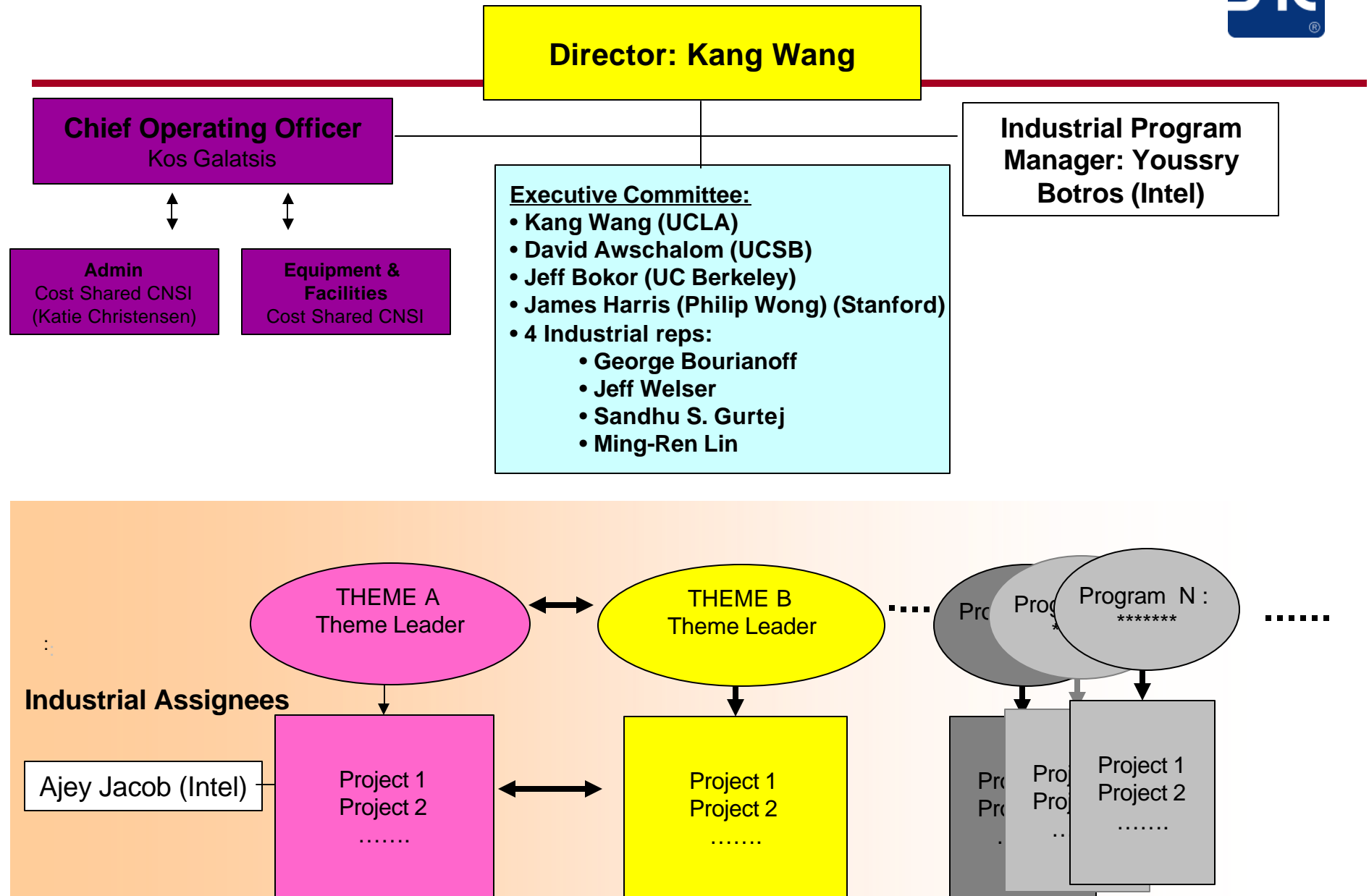
NSF/NRI Supplemental Awards: 2005



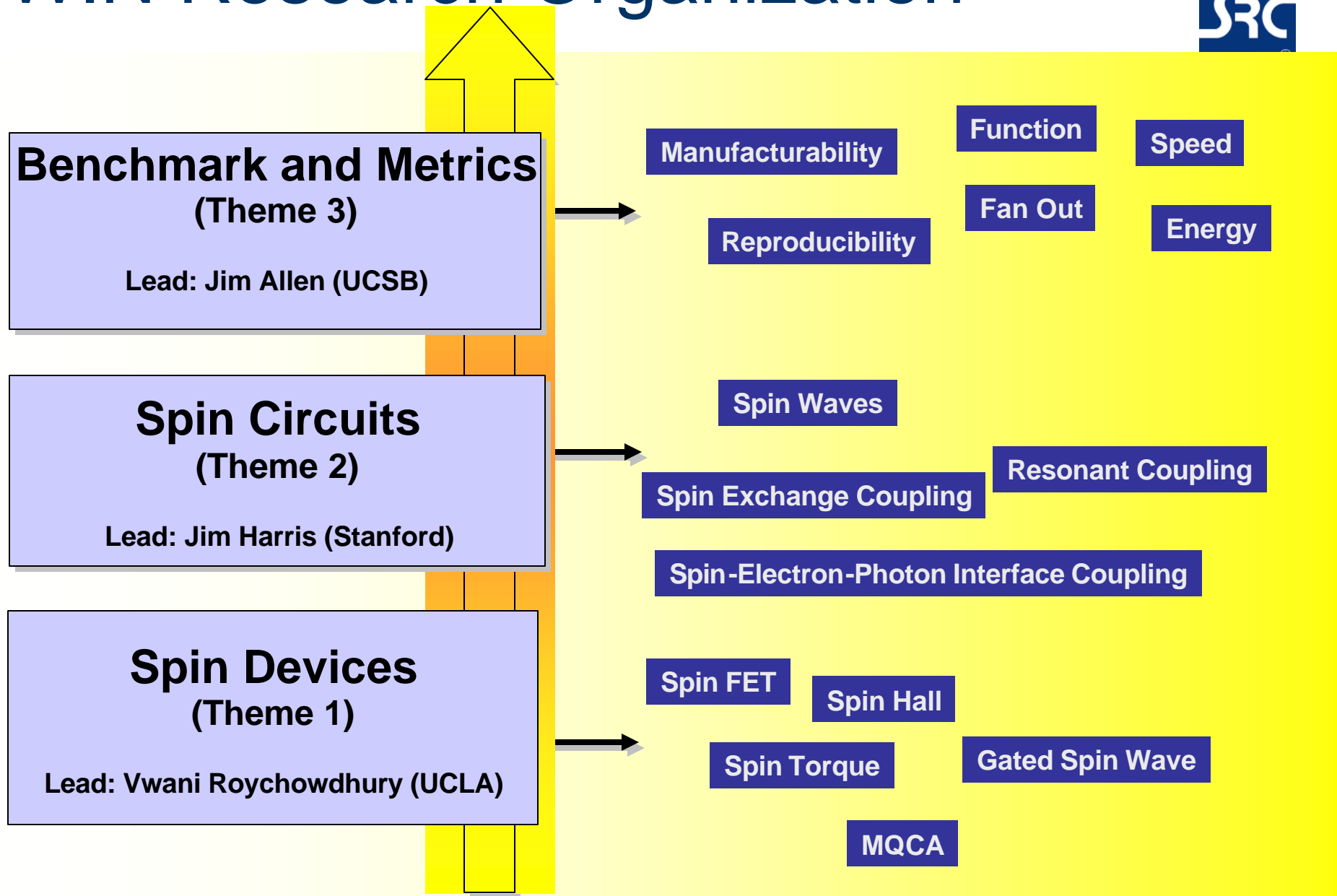
PI	Institution	Center	Center Name	Title of Supplement
Lundstrom, Mark	Purdue U	NCN	Network for Computational Nanotechnology	Exploratory Theory, Modeling, and Simulation for the NRI
Yardley, James T.	Columbia U	NSEC	Columbia Center for Electronic Transport in Molecular nanostructures	Non-equilibrium Quantum Coherent Devices in 1-D materials
Westervelt, Robert	Harvard U	NSEC	Science of Nanoscale Systems and their Device Applications	Ultrasmall Nanowire and Oxide Switches
Hawker, Craig	UCSB (Stanford, U Mass)	MRSEC	MRSEC at UCSB	Development of Next Generation Devices using Nanolithographic Techniques
Hull, Robert	U Virginia (Notre Dame)	MRSEC	Center for Nanoscopic Materials	Directed Assembly of Epitaxial Semiconductor Nanostructures for Novel Logic Switches
Johnson, Matt	U. Arkansas/ U Oklahoma	MRSEC	Center for Semiconductor Physics in Nanostructures	Nanoferroelectric Random Access Memory

NSF issued new RFP on 8/18/06 for new set of awards

WIN Organizational Structure



WIN Research Organization



INDEX Details



◆ Structure

- ❖ Headquartered at UAlbany-CNSE
- ❖ 7 university partners: UA, MIT, GIT, Harvard, Purdue, RPI, Yale
- ❖ Lead PIs: A. Kaloyeros, D. Antoniadis, and J. Meindl
- ❖ Work divided into 5 tasks
 - *Task I: Novel computing State Variable Devices*
 - *Task II: Fabrication and Self-assembly*
 - *Task III: Modeling and Architecture*
 - *Task IV: Theory and Simulation*
 - *Task V: Strategy and Roadmap*

◆ Timeline

- ❖ Year 1: Emphasis on Tasks I & II
- ❖ Year 2: Add Task III
- ❖ Year 3: Add Tasks IV & V

◆ Management

- ❖ Leadership Council with academic and industrial representatives
- ❖ Technical advisory group from industry

INDEX Technical Program and Funding



◆ Research Areas

- ❖ *Task I: Novel computing State Variable Devices*
 - *Magnetoresistive devices using magnetic flux quantum as state variable*
 - *Spintronic single electron transistors based on the Rashba Effect*
 - *Non-volatile logical switches based on the giant planar Hall Effect*
 - *Molecular-mechanical relays using voltage dependent ion channels*
 - *Graphene nanowire switches*
 - *Metal-arene based molecular conformational switches*
- ❖ *Task II: Fabrication and Self-assembly*
 - *Focus for the first 3 years is on fabrication techniques for the Task I devices*
 - *This task is responsible for coordination between the facilities*
- ❖ *Task III: Modeling and Architecture*

SWAN Team



- ◆ **Coordinator / Lead PI: Sanjay Banerjee (UT-Austin)**
- ◆ **University of Texas (Austin)**
 - ❖ Alan MacDonald, Mathew Gilbert, Frank Register
- ◆ **University of Texas at Dallas**
 - ❖ Bruce Gnade, Moon Kim
- ◆ **Texas A& M University**
 - ❖ Jairo Sinova
- ◆ **Rice University**
 - ❖ Yehia Massoud, Peter Nordlander, Naomi Halas
- ◆ **University of Maryland**
 - ❖ Sankar DasSarma
- ◆ **Notre Dame**
 - ❖ Wolfgang Porod and Gary Bernstein
- ◆ **Arizona State University**
 - ❖ John Shumway
- ◆ Plan to establish additional relationships with Oak Ridge National Labs, NASA JSC, and potentially other schools / national labs

SWAN Tasks and Investigators

- ◆ **LEAD PI: Prof. Sanjay Banerjee, UT-Austin**
- ◆ **Task 1: Logic Devices based on new computational state variables**
 - ❖ **UT: Banerjee, Gilbert, MacDonald, Register; Maryland: DasSarma, TAMU: Sinova, ASU: Shumway**
- ◆ **Task 2: Novel materials and structures**
 - ❖ **TAMU: Sinova; Notre Dame: Porod, , Bernstein; UT: Gilbert, Banerjee, Maryland: DasSarma**
- ◆ **Task 3: Directed Self-assembly and nanoscale thermal management**
 - ❖ **UT: Gilbert, Register, Banerjee; Maryland: DasSarma**
- ◆ **Task 4: Novel interconnect and architectures**
 - ❖ **Rice: Massoud, Nordlander, Halas**
- ◆ **Task 5: Nanoscale Characterization**
 - ❖ **UT Dallas: Gnade/Kim**

Conclusions

- Silicon CMOS logic will be extended at least another 10 years.
 - New materials and transistor structures
 - Cooperative circuit and device technology co-design
- New non-silicon memory devices are poised to enter the market.
- The “ultimate FET” may not contain silicon.
- NRI will promote the search for logic devices “beyond the FET”.
- Prediction: Research looking “beyond the FET” will converge on
 - Energy-conserving dynamical systems best suited for implementation of adiabatic switching and reversible logic.
 - Novel circuit architectures designed to allow reliable computation with unreliable devices.